

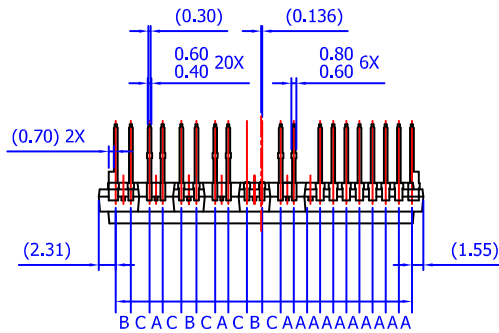
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

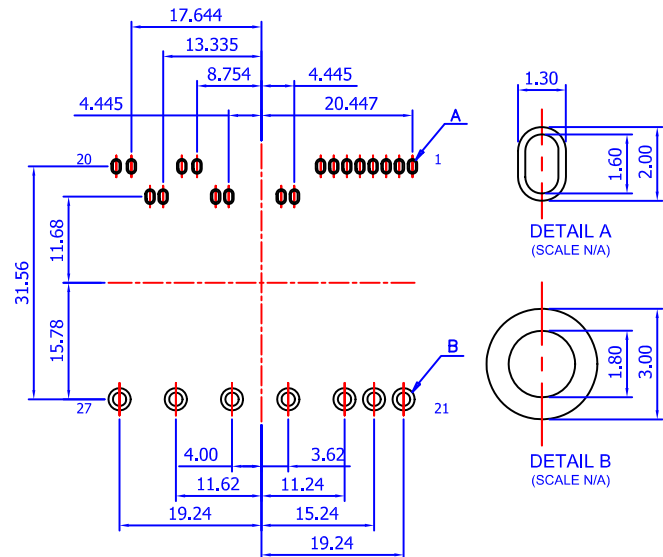
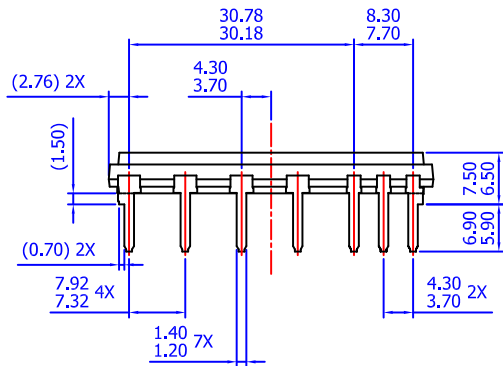
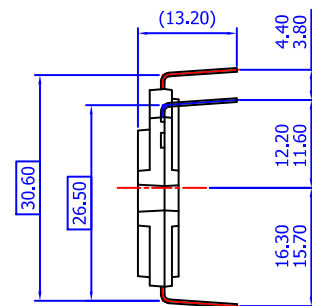
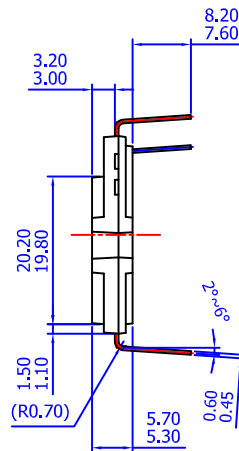
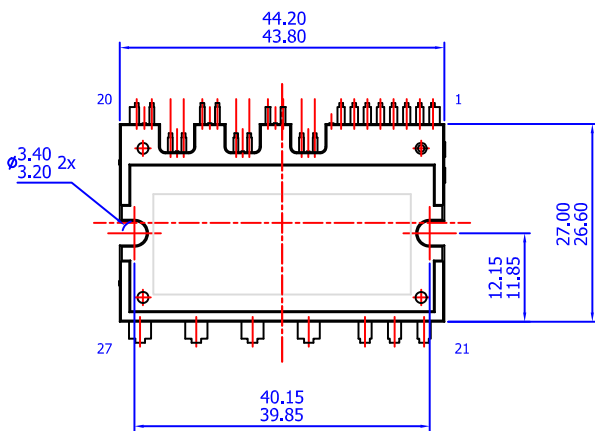


## SPMIA-027 / 27LD, PDD, BOOST PFCM SPM27-IA CASE MODDJ ISSUE O

DATE 31 DEC 2016



LEAD PITCH (TOLERANCE : ±0.30)  
A : 1.778  
B : 2.050  
C : 2.531



LAND PATTERN RECOMMENDATIONS

- NOTES: UNLESS OTHERWISE SPECIFIED  
 A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD  
 B) ALL DIMENSIONS ARE IN MILLIMETERS  
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS  
 D) ( ) IS REFERENCE  
 E) [ ] IS ASS'Y QUALITY

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SPMIA-027 / 27LD, PDD, BOOST PFCM SPM27-IA	PAGE 1 OF 2

